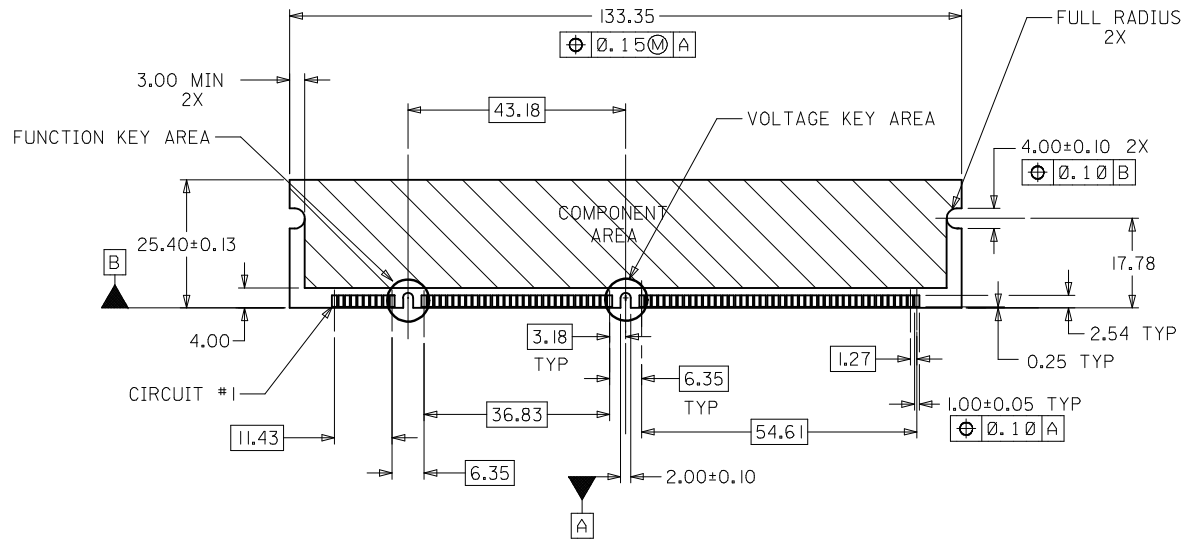


NOTES:

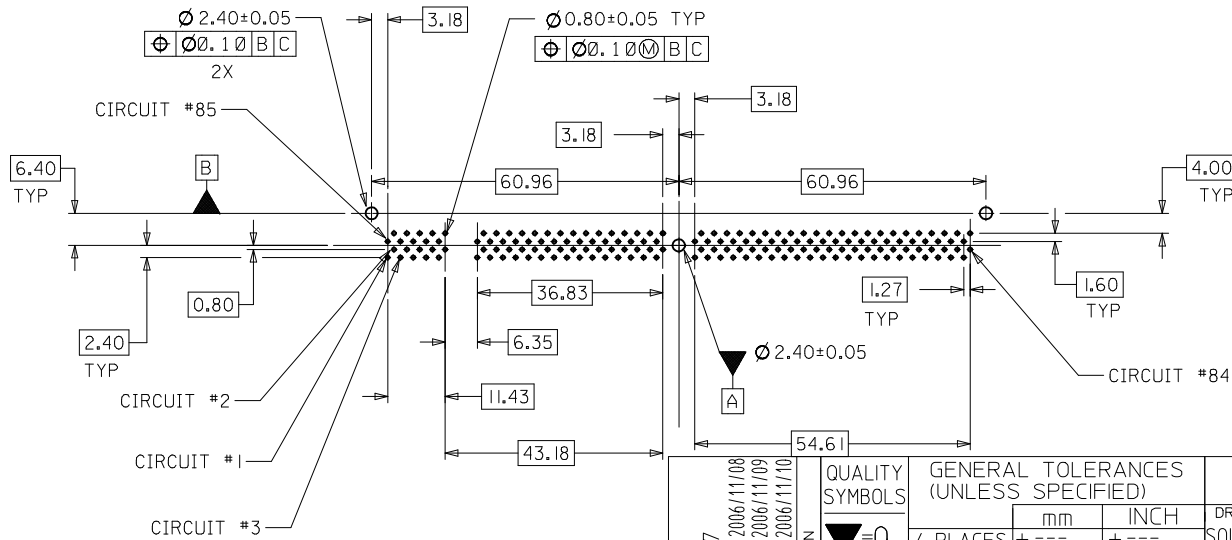
1. PRODUCT SPEC PS-87609-002 APPLIES.
2. PRODUCT IS PACKAGED IN TRAYS.
3. MATERIALS:
 HOUSING, COVER & BASEPLATE - LCP, GLASS FILLED, UL 94V-0, COLOR: BLACK
 TERMINAL - PHOSPHOR BRONZE
 LATCHES - HIGH-TEMP NYLON, GLASS FILLED, UL 94V-0, COLOR: BEIGE
 FORCKLOCKS - COPPER ALLOY OR STEEL ALLOY

4. PLATING:
 CONTACT AREA:
 SEE TABLE ON SHEET 3 OF 3
 FOR GOLD PLATING OPTION AT CONTACT AREA
 SOLDER TAIL: 75μN./(.194μM) MIN. TIN
 UNDERPLATE: 50μN./(.127μM) MIN. NICKEL

VOID P/N EC NO: S2007-0207 DRWN:SKANG 2006/11/08 CHKD:MLONG 2006/11/09 APPR:SKTOH 2006/11/10	DESCRIPTION QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY SQUEK	DATE 2000/01/21	TITLE DDR DIMM, 1.27MM PITCH 168 CKTS, R/A			
		4 PLACES	± ---	± ---	CHECKED BY KCLING	DATE 2000/03/01	MOLEX INCORPORATED DOCUMENT NO. SD-87609-001			
		3 PLACES	± ---	± ---	APPROVED BY SKTOH	DATE 2000/03/03				
2 PLACES	± 0.25	± ---	ANGULAR ± 5 °		MATERIAL NO.		SHEET NO. 1 OF 3			
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

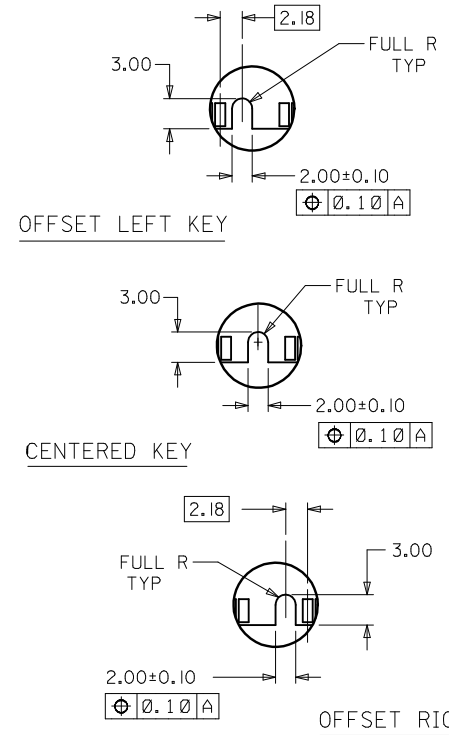


RECOMMENDED MODULE LAYOUT
(PER JEDEC STANDARD MO-161, 168 CKT. 3.3V)



RECOMMENDED P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)

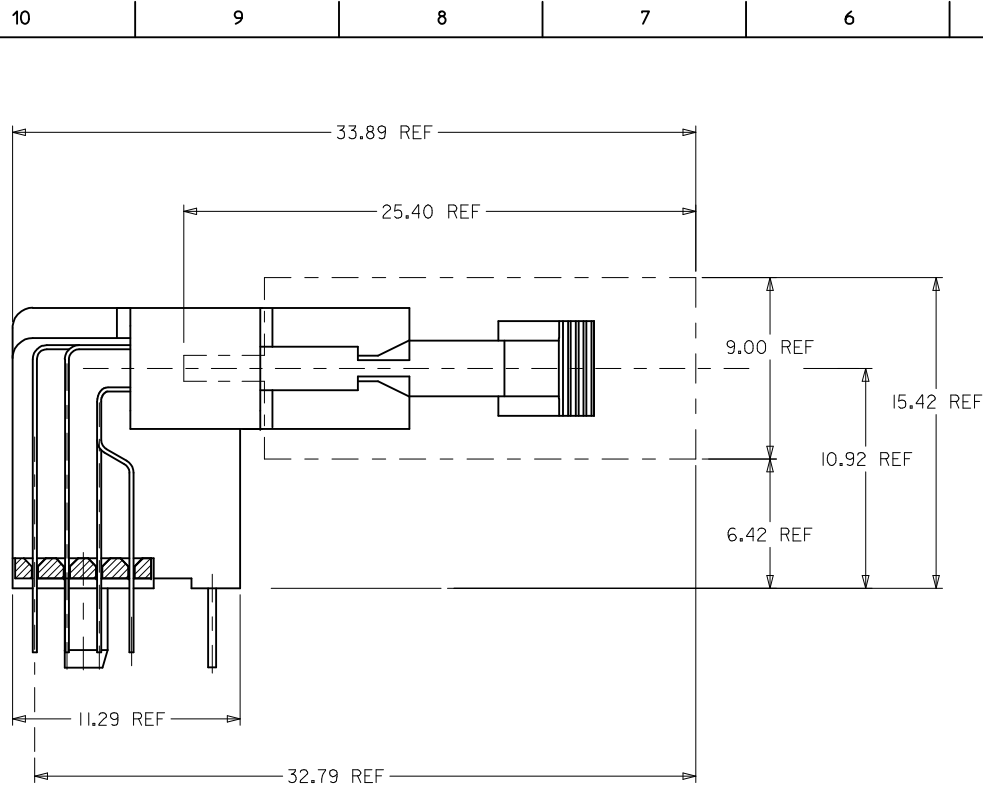
FUNCTION KEY AREA OPTIONS
(REFER ALSO TO TABLE ON SHT. 3)



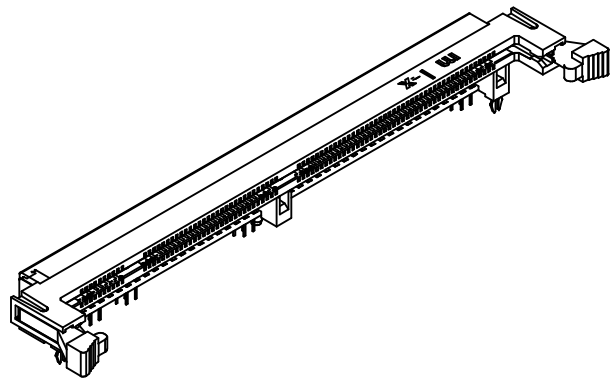
NOTES:

1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP 4.00(157)
2. RECOMMENDED PLATING ON MODULE PADS: 0.76 MICROMETER(30 MICROINCH) MINIMUM HARD GOLD OVER 2.0 MICROMETER(79 MICROINCH) MINIMUM NICKEL.

VOID P/N EC NO: S2007-0207 DRWN:SKANG CHKD:MLONG APPR:SKTOH 2006/11/08 2006/11/09 2006/11/10	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY SQUEK	DATE 2000/01/21	TITLE DDR DIMM, 1.27MM PITCH 168 CKTS, R/A		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		APPROVED BY SKTOH	DATE 2000/03/03	MOLEX INCORPORATED			
		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		SD-87609-001 2 OF 3			



ACTUAL MODULE HEIGHT AND CLEARANCE
WHEN USING A 9.00MM THICK BY 25.40MM HEIGHT
MODULE (TYPICAL SOJ PACKAGING).



PART NUMBER	FUNCTION KEY	GOLD PLATING OPTION AT CONTACT AREA	DATUM VOLTAGE KEY	TAIL LENGTH P±0.25	RECOMMENDED PCB THICKNESS
87609-0051	LEFT	15µN/(0.38µM) MIN.	CENTER (3.3V)	2.79	1.57
87609-0052	CENTRE				
87609-0053	RIGHT				
87609-0151	LEFT	30µN/(0.76µM) MIN.	CENTER (3.3V)	3.18	2.36
87609-0152	CENTRE				
87609-0153	RIGHT				
87609-0061	CENTRE	15µN/(0.38µM) MIN.	CENTER (3.3V)	3.56	2.79
87609-0062	RIGHT				
87609-0162	RIGHT	30µN/(0.76µM) MIN.			
87609-0069	LEFT	15µN/(0.38µM) MIN.	CENTER (3.3V)	3.56	2.79
87609-0070	CENTRE				
87609-0071	RIGHT				
87609-0171	RIGHT	30µN/(0.76µM) MIN.			

VOID P/N EC NO: S2007-0207 DRWN:SKANG 2006/11/08 CHKD:MLONG 2006/11/09 APPR:SKTOH 2006/11/10	QUALITY SYMBOLS =0 =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				DRAWN BY: SQUEK DATE: 2000/01/21	TITLE DDR DIMM, 1.27MM PITCH 168 CKTS, R/A				
				4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± ---	CHECKED BY: KCLING DATE: 2000/03/01	MOLEX INCORPORATED			
				ANGULAR ± 5 °	APPROVED BY: SKTOH DATE: 2000/03/03	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87609-001	SHEET NO. 3 OF 3	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							